KUNLUN WU

116th and Broadway, New York | 2032607333 | kw3037@columbia.edu | https://kunlun-wu.github.io/

EDUCATION

Columbia University New York, NY

MS in Materials Science and Engineering Ongoing, expected graduation in Dec 2025

Columbia University New York, NY May 2024

BS in Materials Science and Engineering, 3.6/4.0

Dean's List

Colgate University Hamilton, NY May 2024

BA in Physics and Japanese, 3.8/4.0

Dean's Award with Distinction

EXPERIENCE

Columbia University: School of Engineering

Nanoparticle Lab Undergraduate Researcher (PI: Siu-Wai Chan)

Aug 2023 - May 2024

- Low temperature conductivity of copper-doped nanoceria
 - o Area: Materials Science, Ceramics, Nanoparticles
 - o Led a small team of 4 students
 - o Co-precipitated 6 groups of copper-doped nanoceria with various concentrations
 - o Characterized conductivity through impedance spectroscopy (EIS) measurements at 6 temperatures
- Refractive index modification on flexible and transparent thin films using nanoceria
 - o Area: Materials Science, Photonics, Thin Films
 - o Collaborated with Professor Nanfang Yu's optics lab
 - Produced 6 groups of SU8+thinner precursors with various concentrations of ~10 and 35 nm nanoparticles
 - Conducted dynamic light scattering (DLS) measurements
 - Analyzed 36 sets of ellipsometry measurements from spin coated films on Si substrate

Optics Lab Researcher (PI: Nanfang Yu)

Aug 2024 - Present

New York, NY

- Machine learning model on refractive index enhancement SU8 thin films using metal salts
 - Area: Materials Science, Photonics, Thin Films, Machine Learning
 - Ongoing

Oriental Fortune Capital: Shanghai Branch

Assistant Investment Manager (Intern)

Shanghai, CN

Jun 2023 - Aug 2023

- Produced market research on Chinese domestic in-vehicle MCU industry from 2022 to 2023
- Developed an investment analysis on 9 companies of interest with constructed an evaluation method spanning across 5 key areas

HONORARY SOCIETIES

Materials Research Society: CU Student Chapter

New York, NY Aug 2023 - Dec 2023 Vice President President Jan 2024 - Present

Materials Advantage: CU Student Chapter

New York, NY Vice President Aug 2023 - Dec 2023 President Jan 2024 - Present

SKILLS

- Chinese (Native)
- Japanese (Proficient)